

Title (en)
METHODS FOR PROCESSING PRINTED SUBSTRATES

Publication
EP 0518621 A3 19930331 (EN)

Application
EP 92305286 A 19920609

Priority
US 71282791 A 19910610

Abstract (en)
[origin: EP0518621A2] Methods for processing substrates printed with an ink layer having a non-planar surface topography, eg curved ink droplets, to produce a composite laminate and the composite laminates produced thereby are disclosed. A printed substrate is laminated to a transparent film using an intermediate adhesive layer. During lamination processing, the adhesive layer conforms to the surface topography of the printed ink layer, while the conformation of the printed ink layer remains substantially unchanged. The lamination processing methods are especially suitable for processing light transmissive substrates, such as transparencies, printed with phase change color inks to produce composite laminates that project clear, color saturated images upon overhead projection. <IMAGE>

IPC 1-7
B41J 2/01; **B41M 7/00**

IPC 8 full level
B41J 29/00 (2006.01); **B41J 2/01** (2006.01); **B41M 5/00** (2006.01); **B41M 7/00** (2006.01)

CPC (source: EP)
B41J 2/01 (2013.01); **B41M 7/0027** (2013.01)

Citation (search report)
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Designated contracting state (EPC)
DE FR GB IT

DOCDB simple family (publication)
EP 0518621 A2 19921216; **EP 0518621 A3 19930331**; **EP 0518621 B1 19961211**; DE 69215763 D1 19970123; DE 69215763 T2 19970710; JP 2528772 B2 19960828; JP H07101172 A 19950418

DOCDB simple family (application)
EP 92305286 A 19920609; DE 69215763 T 19920609; JP 17607692 A 19920610